

ABSTRACT OF THE DISCLOSURE

An apparatus and method for preventing damage to tape attachment semiconductor assemblies due to encapsulation filler particles causing damage to a semiconductor die active surface and/or to a corresponding semiconductor substrate surface by providing an adhesive tape which extends across areas of contact between the semiconductor die active surface and the semiconductor substrate. The present invention also includes extending the adhesive tape beyond the areas of contact between the semiconductor die active surface and the semiconductor substrate to provide a visible surface of visual inspection of proper adhesive tape placement.

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